



**PGA204 PGA205** 

# Programmable Gain INSTRUMENTATION AMPLIFIER

## **FEATURES**

- DIGITALLY PROGRAMMABLE GAIN:
   PGA204: G=1, 10, 100, 1000V/V
   PGA205: G=1, 2, 4, 8V/V
- LOW OFFSET VOLTAGE: 50µV max
- LOW OFFSET VOLTAGE DRIFT: 0.25μV/°C
- LOW INPUT BIAS CURRENT: 2nA max
- LOW QUIESCENT CURRENT: 5.2mA typ
- NO LOGIC SUPPLY REQUIRED
- 16-PIN PLASTIC DIP. SOL-16 PACKAGES

## **APPLICATIONS**

- DATA ACQUISITION SYSTEM
- GENERAL PURPOSE ANALOG BOARDS
- MEDICAL INSTRUMENTATION

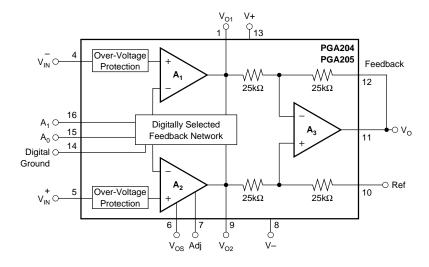
## **DESCRIPTION**

The PGA204 and PGA205 are low cost, general purpose programmable-gain instrumentation amplifiers offering excellent accuracy. Gains are digitally selected: PGA204—1, 10, 100, 1000, and PGA205—1, 2, 4, 8V/V. The precision and versatility, and low cost of the PGA204 and PGA205 make them ideal for a wide range of applications.

Gain is selected by two TTL or CMOS-compatible address lines,  $A_0$  and  $A_1$ . Internal input protection can withstand up to  $\pm 40$ V on the analog inputs without damage.

The PGA204 and PGA205 are laser trimmed for very low offset voltage ( $50\mu V$ ), drift ( $0.25\mu V/^{\circ}C$ ) and high common-mode rejection (115dB at G=1000). They operate with power supplies as low as  $\pm 4.5V$ , allowing use in battery operated systems. Quiescent current is 5mA.

The PGA204 and PGA205 are available in 16-pin plastic DIP, and SOL-16 surface-mount packages, specified for the -40°C to +85°C temperature range.



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## **SPECIFICATIONS**

## **ELECTRICAL**

PGA204 G=1, 10, 100, 1000V/V

At T<sub>A</sub> = +25°C, V<sub>S</sub> =  $\pm 15$ V, and R<sub>L</sub> =  $2k\Omega$  unless otherwise noted.

		P	PGA204BP, BU		F	GA204AP, A	U	
PARAMETER	CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
INPUT Offset Voltage, RTI vs Temperature vs Power Supply Long-Term Stability Impedance, Differential	$T_A$ =+25°C $T_A$ = $T_{MIN}$ to $T_{MAX}$ $V_S$ =±4.5V to ±18V		±10+20/G ±0.1+0.5/G 0.5+2/G ±0.2+0.5/G 10 <sup>10</sup>   6	±50+100/G ±0.25+5/G 3+10/G		±25+30/G ±0.25+5/G * * *	±125+500/G ±1+10/G *	μV μV/°C μV/V μV/mo Ω    pF
Common-Mode Input Common-Mode Range Safe Input Voltage Common-Mode Rejection	$V_O=0V$ (see text) $V_{CM}=\pm 10V, \ \Delta R_S=1k\Omega$	±10.5	10 <sup>10</sup>   6 ±12.7	±40	*	*	*	Ω    pF V V
Common mode regional.	G=1 G=10 G=100 G=1000	80 96 110 115	99 114 123 123		75 90 106 106	90 106 110 110		dB dB dB dB
BIAS CURRENT vs Temperature Offset Current vs Temperature			±0.5 ±8 ±0.5 ±8	±2 ±2		* * *	±5 *	nA pA/°C nA pA/°C
NOISE, Voltage, RTI <sup>(1)</sup> : f=10Hz f=100Hz f=1kHz f <sub>B</sub> =0.1Hz to 10Hz Noise Current f=10Hz	$G≥100, R_S=0Ω$ $G≥100, R_S=0Ω$ $G≥100, R_S=0Ω$ $G≥100, R_S=0Ω$ $G≥100, R_S=0Ω$		16 13 13 0.4			* * * *		nV/√Hz nV/√Hz nV/√Hz μVp-p pA/√Hz
f=1kHz f <sub>B</sub> =0.1Hz to 10Hz			0.2			*		pA/√Hz pAp-p
GAIN, Error  Gain vs Temperature  Nonlinearity	G=1 G=10 G=100 G=1000 G=1 to 1000 G=1 G=10 G=100 G=1000		±0.005 ±0.01 ±0.01 ±0.02 ±2.5 ±0.0004 ±0.0004 ±0.0004	±0.024 ±0.024 ±0.024 ±0.05 ±10 ±0.001 ±0.002 ±0.002 ±0.01		* * * * * * * * * * * *	±0.05 ±0.05 ±0.05 ±0.1 * ±0.002 ±0.004 ±0.004	% % % ppm/°C % of FSR % of FSR % of FSR % of FSR
OUTPUT Voltage, Positive <sup>(2)</sup> Negative <sup>(2)</sup> Load Capacitance Stability Short Circuit Current	$I_{O}$ =5mA, $T_{MIN}$ to $T_{MAX}$ $I_{O}$ =-5mA, $T_{MIN}$ to $T_{MAX}$	(V+)-1.5 (V-)+1.5	(V+)-1.3 (V-)+1.3 1000 +23/-17		*	* * *		V V pF mA
FREQUENCY RESPONSE Bandwidth, -3dB  Slew Rate Settling Time <sup>(3)</sup> , 0.1%  0.01%  Overload Recovery	G=1 G=10 G=100 G=1000 V <sub>O</sub> =±10V, G=10 G=1 G=10 G=100 G=1000 G=1 G=100 G=1000 G=1000 S=000 G=1000	0.3	1 80 10 1 0.7 22 23 100 1000 23 28 140 1300 70		٠			MHz kHz kHz kHz V/µs µs µs µs µs µs µs µs
DIGITAL LOGIC Digital Ground Voltage, V <sub>DG</sub> Digital Low Voltage Digital Input Current Digital High Voltage		V- V- V <sub>DG</sub> +2	1	(V+)-4 V <sub>DG</sub> +0.8V V+	* *	*	* *	V V μΑ V
POWER SUPPLY, Voltage Current	V <sub>IN</sub> =0V	±4.5	±15 +5.2/–4.2	±18 ±6.5	*	*	* ±7.5	V mA
TEMPERATURE RANGE Specification Operating $\theta_{\mathrm{JA}}$		-40 -40	80	+85 +125	*	*	*	°C °C °C/W

<sup>\*</sup> Specification same as PGA204BP.

NOTES: (1) Input-referred noise voltage varies with gain. See typical curves. (2) Output voltage swing is tested for  $\pm 10$ V min on  $\pm 11.4$ V power supplies. (3) Includes time to switch to a new gain.



## **SPECIFICATIONS**

## **ELECTRICAL**

PGA205 G=1, 2, 4, 8V/V

At T<sub>A</sub> = +25°C, V<sub>S</sub> =  $\pm 15$ V, and R<sub>L</sub> =  $2k\Omega$  unless otherwise noted.

		Р	GA205BP, BI	J	PGA205AP, AU			
PARAMETER	CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
INPUT Offset Voltage, RTI vs Temperature vs Power Supply Long-Term Stability Impedance, Differential Common-Mode Input Common-Mode Range Safe Input Voltage Common-Mode Rejection	$T_A$ =+25°C $T_A$ = $T_{MIN}$ to $T_{MAX}$ $V_S$ =±4.5V to ±18V $V_O$ =0V (see text) $V_{CM}$ =±10V, $\Delta R_S$ =1k $\Omega$	±10.5	±10+20/G ±0.1+0.5/G 0.5+2/G ±0.2+0.5/G 10 <sup>10</sup>   6 10 <sup>10</sup>   6 ±12.7	±50+100/G ±0.25+5/G 3+10/G	*	±25+30/G ±0.25+5/G * * * *	±125+500/G ±1+10/G *	μV μV/°C μV/V μV/mo Ω  pF Ω  pF V V
	G=1 G=2 G=4 G=8	80 85 90 95	94 100 106 112		75 80 85 89	88 94 100 106		dB dB dB dB
BIAS CURRENT vs Temperature Offset Current vs Temperature			±0.5 ±8 ±0.5 ±8	±2 ±2		* * *	±5 *	nA pA/°C nA pA/°C
Noise Voltage, RTI <sup>(1)</sup> : $f=10Hz$ f=100Hz f=1KHz $f_B=0.1Hz$ to $10Hz$ Noise Current f=10Hz f=1kHz $f_B=0.1Hz$ to $10Hz$	G=8, $R_S$ =0 $\Omega$ G=8, $R_S$ =0 $\Omega$ G=8, $R_S$ =0 $\Omega$ G=8, $R_S$ =0 $\Omega$		19 15 15 0.5 0.4 0.2 18			* * * * * * * * * * * * * * * * * * * *		nV/√Hz nV/√Hz nV/√Hz μVp-p pA/√Hz pA/√Hz
GAIN, Error  Gain vs Temperature Nonlinearity	G=1 G=2 G=4 G=8 G=1 to 8 G=1 G=2 G=4 G=8		±0.005 ±0.01 ±0.01 ±0.01 ±2.5 ±0.00024 ±0.00024 ±0.00024	±0.024 ±0.024 ±0.024 ±0.024 ±10 ±0.001 ±0.002 ±0.002 ±0.002		* * * * * * * * * * * * * * * * * * * *	±0.05 ±0.05 ±0.05 ±0.05 * ±0.002 ±0.004 ±0.004	pAp-p  % % % ppm/°C % of FSR
OUTPUT  Voltage, Positive <sup>(2)</sup> Negative <sup>(2)</sup> Load Capacitance Stability  Short Circuit Current	I <sub>O</sub> =5mA, T <sub>MIN</sub> to T <sub>MAX</sub> I <sub>O</sub> =-5mA, T <sub>MIN</sub> to T <sub>MAX</sub>	(V+)-1.5 (V-)+1.5	(V+)-1.3 (V-)+1.3 1000 +23/-17		*	* * *		V V pF mA
FREQUENCY RESPONSE Bandwidth, -3dB  Slew Rate Settling Time(3), 0.1%  0.01%  Overload Recovery  DIGITAL LOGIC INPUTS	G=1 G=2 G=4 G=8 V <sub>O</sub> =±10V, G=8 G=1 G=2 G=4 G=8 G=1 G=2 G=4 G=8 50% overdrive	0.3	1 400 200 100 0.7 22 22 23 23 23 23 23 25 28 70		*			MHz kHz kHz kHz kHz v/  kHz us  us  us  us  us  us  us  us  us  us
Digital Ground Voltage, V <sub>DG</sub> Digital Low Voltage Digital Low Current Digital High Voltage		V- V- V <sub>DG</sub> +2	1	(V+)-4 V <sub>DG</sub> +0.8V V+	* *	*	* *	V V μΑ V
POWER SUPPLY, Voltage Current	V <sub>IN</sub> =0V	±4.5	±15 +5.2/–4.2	±18 ±6.5	*	*	* ±7.5	V mA
		-40 -40	80	+85 +125	*	*	*	°C °C °C

<sup>\*</sup> Specification same as PGA204BP.

NOTES: (1) Input-referred noise voltage varies with gain. See typical curves. (2) Output voltage swing is tested for  $\pm 10$ V min on  $\pm 11.4$ V power supplies. (3) Includes time to switch to a new gain.



## **PACKAGE INFORMATION**

MODEL	PACKAGE	PACKAGE DRAWING NUMBER <sup>(1)</sup>
PGA204AP	16-Pin Plastic DIP	180
PGA204BP	16-Pin Plastic DIP	180
PGA204AU	SOL-16 Surface Mount	211
PGA204BU	SOL-16 Surface Mount	211
PGA205AP	16-Pin Plaseic DIP	180
PGA205BP	16-Pin Plastic DIP	180
PGA205AU	SOL-16 Surface Mount	211
PGA205BU	SOL-16 Surface Mount	211

NOTE: (1) For detailed drawing and dimension table, please see end of data sheet, or Appendix D of Burr-Brown IC Data Book.

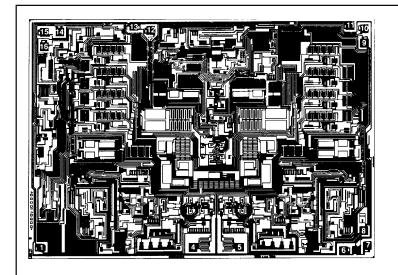
## **ABSOLUTE MAXIMUM RATINGS**

Supply Voltage	
Analog Input Voltage Range	
Logic Input Voltage Range	±V <sub>S</sub>
Output Short-Circuit (to ground)	Continuous
Operating Temperature	40°C to +125°C
Storage Temperature	40°C to +125°C
Junction Temperature	+150°C
Lead Temperature (soldering -10s)	+300°C

## **ORDERING INFORMATION**

MODEL	GAINS	PACKAGE	TEMPERATURE RANGE
PGA204AP	1, 10, 100, 1000V/V	16-Pin Plastic DIP	-40 to +85°C
PGA204BP	1, 10, 100, 1000V/V	16-Pin Plastic DIP	-40 to +85°C
PGA204AU	1, 10, 100, 1000V/V	SOL-16 Surface-Mount	−40 to +85°C
PGA204BU	1, 10, 100, 1000V/V	SOL-16 Surface-Mount	−40 to +85°C
PGA205AP	1, 2, 4, 8V/V	16-Pin Plastic DIP	-40 to +85°C
PGA205BP	1, 2, 4, 8V/V	16-Pin Plastic DIP	-40 to +85°C
PGA205AU	1, 2, 4, 8V/V	SOL-16 Surface-Mount	-40 to +85°C
PGA205BU	1, 2, 4, 8V/V	SOL-16 Surface-Mount	-40 to +85°C

#### **DICE INFORMATION**



PAD	FUNCTION	PAD	FUNCTION
1	V <sub>O1</sub>	9	V <sub>O2</sub>
2		10	Ref
3	_	11	Vo
4	V- <sub>IN</sub>	12	Feedback
5	V <sup>+</sup> IN	13	V+
6	V <sub>OS</sub> Adj	14	Dig. Ground
7	V <sub>OS</sub> Adj V <sub>OS</sub> Adj V–	15	$A_0$
8	V-	16	A <sub>1</sub>

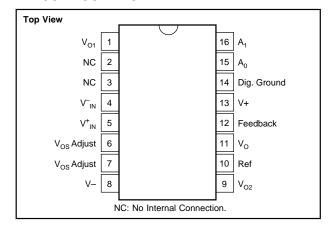
Substrate Bias: Internally connected to V- power supply.

## **MECHANICAL INFORMATION**

	MILS (0.001")	MILLIMETERS
Die Size Die Thickness	186 x 130 ±5 20 +3	4.72 x 3.30 ±0.13 0.51 +0.08
Min. Pad Size	4 x 4	0.1 x 0.1
Backing		Gold

## PGA204/205 DIE TOPOGRAPHY

## **PIN CONFIGURATION**



# ELECTROSTATIC DISCHARGE SENSITIVITY

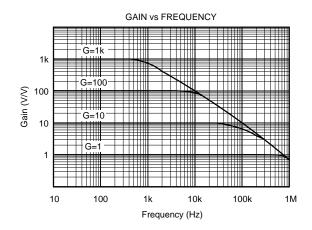
This integrated circuit can be damaged by ESD. Burr-Brown recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

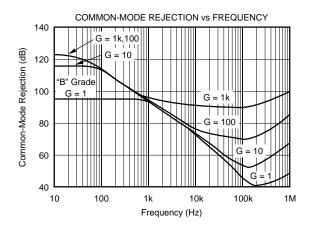
ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

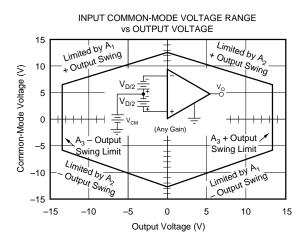
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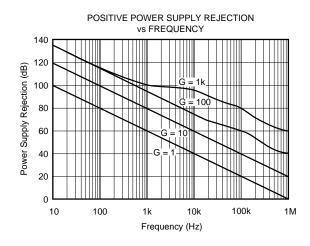
## **TYPICAL PERFORMANCE CURVES**

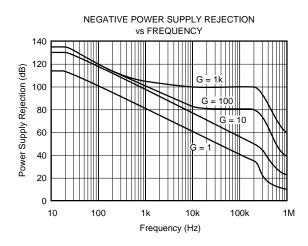
At  $T_A$  = +25°C, and  $V_S$  = ±15V, unless otherwise noted.

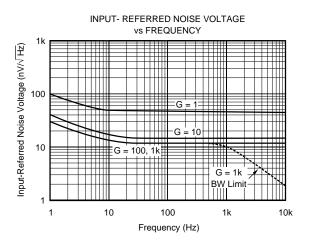






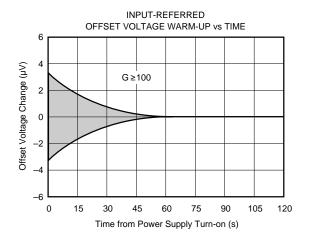


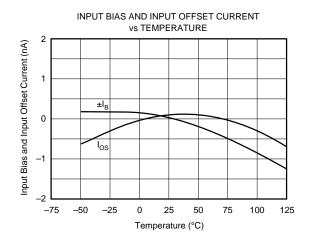


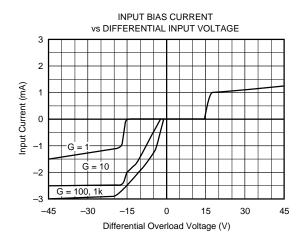


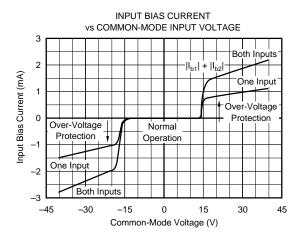


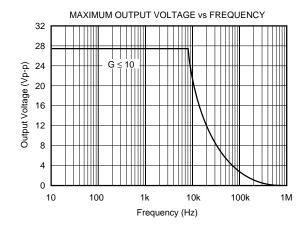
At  $T_A$  = +25°C, and  $V_S$  = ±15V, unless otherwise noted.

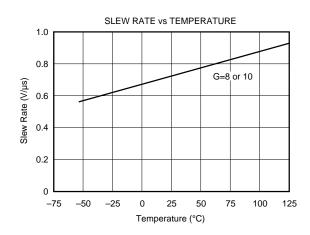




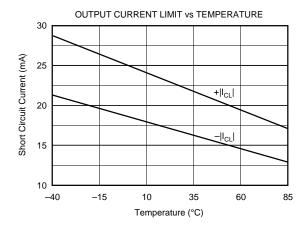


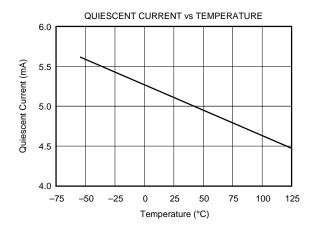


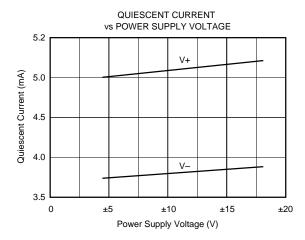


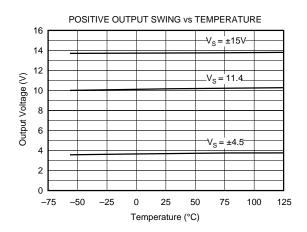


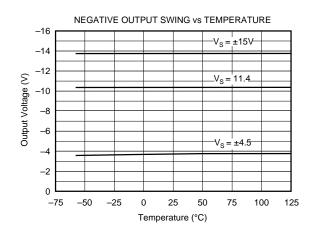
At  $T_A = +25^{\circ}C$ , and  $V_S = \pm 15V$ , unless otherwise noted.







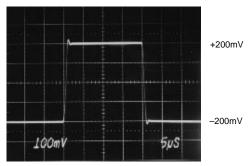




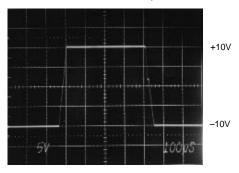


At  $T_A$  = +25°C, and  $V_S$  = ±15V, unless otherwise noted.

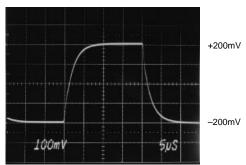
SMALL-SIGNAL RESPONSE, G = 1



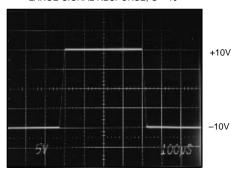
LARGE-SIGNAL RESPONSE, G = 1



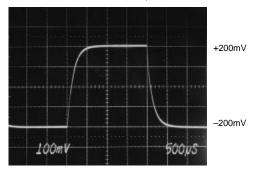
SMALL-SIGNAL RESPONSE, G = 10



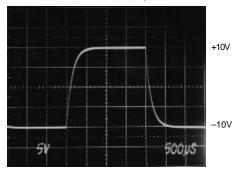
LARGE-SIGNAL RESPONSE, G = 10



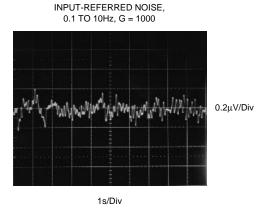
SMALL-SIGNAL RESPONSE, G = 1000

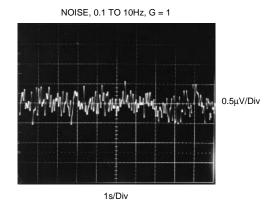


LARGE-SIGNAL RESPONSE, G = 1000



At  $T_A$  = +25°C, and  $V_S$  = ±15V, unless otherwise noted.





## APPLICATION INFORMATION

Figure 1 shows the basic connections required for operation of the PGA204/205. Applications with noisy or high impedance power supplies may require decoupling capacitors close to the device pins as shown.

The output is referred to the output reference (Ref) terminal which is normally grounded. This must be a low-impedance connection to assure good common-mode rejection. A resistance of  $5\Omega$  in series with the Ref pin will cause a typical device to degrade to approximately 80dB CMR (G=1).

The PGA204/205 has an output feedback connection (pin 12). Pin 12 must be connected to the output terminal (pin 11) for proper operation. The output Feedback connection can

be used to sense the output voltage directly at the load for best accuracy.

#### **DIGITAL INPUTS**

The digital inputs  $A_0$  and  $A_1$  select the gain according to the logic table in Figure 1. Logic "1" is defined as a voltage greater than 2V above digital ground potential (pin 14). Digital ground can be connected to any potential from the V– power supply to 4V less than V+. Digital ground is normally connected to ground. The digital inputs interface directly CMOS and TTL logic components.

Approximately  $1\mu A$  flows out of the digital input pins when a logic "0" is applied. Logic input current is nearly zero with a logic "1" input. A constant current of approximately

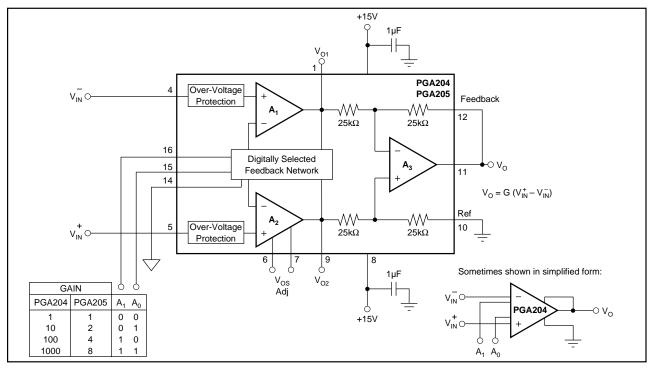


FIGURE 1. Basic Connections.

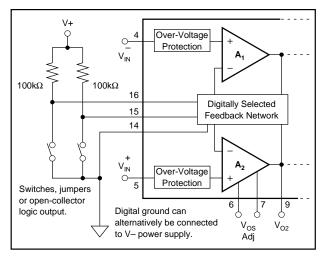


FIGURE 2. Switch or Jumper-Selected Digital Inputs.

1.3mA flows in the digital ground pin. It is good practice to return digital ground through a separate connection path so that analog ground is not affected by the digital ground current.

The digital inputs,  $A_0$  and  $A_1$ , are not latched; a change in logic inputs immediately selects a new gain. Switching time of the logic is approximately  $1\mu s$ . The time to respond to gain change is effectively the time it takes the amplifier to settle to a new output voltage in the newly selected gain (see settling time specifications).

Many applications use an external logic latch to access gain control data from a high speed data bus (see Figure 7). Using an external latch isolates the high speed digital bus from sensitive analog circuitry. Locate the latch circuitry as far as practical from analog circuitry.

Some applications select gain of the PGA204/205 with switches or jumpers. Figure 2 shows pull-up resistors connected to assure a noise-free logic "1" when the switch, jumper or open-collector logic is open or off. Fixed-gain applications can connect the logic inputs directly to V+ or V- (or other valid logic level); no resistor is required.

#### **OFFSET VOLTAGE**

Voltage offset of the PGA204/205 consists of two components—input stage offset and output stage offset. Both components are specified in the specification table in equation form:

$$V_{OS} = V_{OSI} + V_{OSO} / G$$
 (1)

where:

V<sub>OS</sub> total is the combined offset, referred to the input.

 $V_{OSI}$  is the offset voltage of the input stage,  $A_1$  and  $A_2$ .

 $V_{\rm OSO}$  is the offset voltage of the output difference amplifier,  $A_3$ .

 $V_{OSI}$  and  $V_{OSO}$  do not change with gain. The composite offset voltage  $V_{OS}$  changes with gain because of the gain term in equation 1. Input stage offset dominates in high gain (G $\geq$ 100); both sources of offset may contribute at low gain (G=1 to 10).

#### **OFFSET TRIMMING**

Both the input and output stages are laser trimmed for very low offset voltage and drift. Many applications require no external offset adjustment.

Figure 3 shows an optional input offset voltage trim circuit. This circuit should be used to adjust only the input stage offset voltage of the PGA204/205. Do this by programming

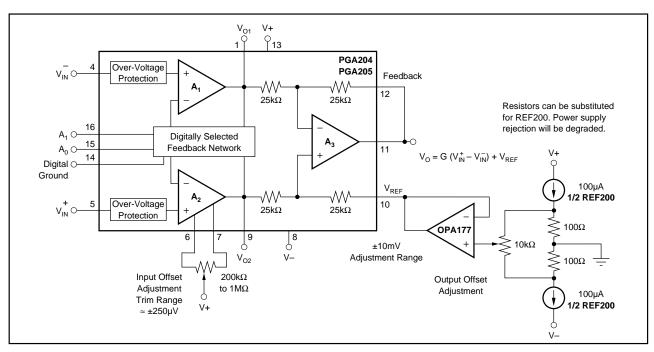


FIGURE 3. Optional Offset Voltage Trim Circuit.

it to its highest gain and trimming the output voltage to zero with the inputs grounded. Drift performance usually improves slightly when the input offset is nulled with this procedure.

Do not use the input offset adjustment to trim system offset or offset produced by a sensor. Nulling offset that is not produced by the input amplifiers will increase temperature drift by approximately  $3.3\mu V/^{\circ}C$  per 1mV of offset adjustment.

Many applications that need input stage offset adjustment do not need output stage offset adjustment. Figure 3 also shows a circuit for adjusting output offset voltage. First, adjust the input offset voltage as discussed above. Then program the device for G=1 and adjust the output to zero. Because of the interaction of these two adjustments at G=8, the PGA205 may require iterative adjustment.

The output offset adjustment can be used to trim sensor or system offsets without affecting drift. The voltage applied to the Ref terminal is summed with the output signal. Low impedance must be maintained at this node to assure good common-mode rejection. This is achieved by buffering the trim voltage with an op amp as shown.

#### **NOISE PERFORMANCE**

The PGA204/205 provides very low noise in most applications. Low frequency noise is approximately  $0.4\mu Vp$ -p measured from 0.1 to 10Hz. This is approximately one-tenth the noise of "low noise" chopper-stabilized amplifiers.

#### INPUT BIAS CURRENT RETURN PATH

The input impedance of the PGA204/205 is extremely high—approximately  $10^{10}\Omega$ . However, a path must be provided for the input bias current of both inputs. This input bias current is typically less than  $\pm 1$ nA (it can be either polarity due to cancellation circuitry). High input impedance means that this input bias current changes very little with varying input voltage.

Input circuitry must provide a path for this input bias current if the PGA204/205 is to operate properly. Figure 4 shows provisions for an input bias current path. Without a bias current return path, the inputs will float to a potential which exceeds the common-mode range of the PGA204/205 and the input amplifiers will saturate. If the differential source resistance is low, bias current return path can be connected to one input (see thermocouple example in Figure 4). With higher source impedance, using two resistors provides a balanced input with possible advantages of lower input offset voltage due bias current and better common-mode rejection.

Many sources or sensors inherently provide a path for input bias current (e.g. the bridge sensor shown in Figure 4). These applications do not require additional resistor(s) for proper operation.

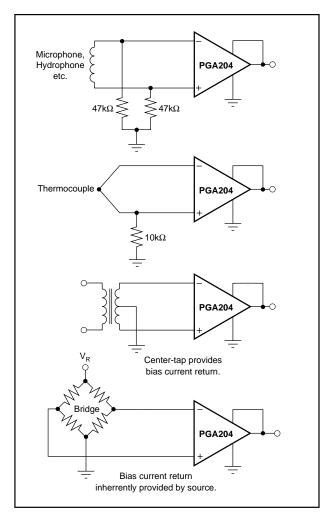


FIGURE 4. Providing an Input Common-Mode Current Path.

## **INPUT COMMON-MODE RANGE**

The linear common-mode range of the input op amps of the PGA204/205 is approximately  $\pm 12.7V$  (or 2.3V from the power supplies). As the output voltage increases, however, the linear input range will be limited by the output voltage swing of the input amplifiers,  $A_1$  and  $A_2$ . The common-mode range is related to the output voltage of the complete amplifier—see performance curve "Input Common-Mode Range vs Output Voltage".

A combination of common-mode and differential input voltage can cause the output of  $A_1$  or  $A_2$  to saturate. Figure 5 shows the output voltage swing of  $A_1$  and  $A_2$  expressed in terms of a common-mode and differential input voltages. Output swing capability of these internal amplifiers is the same as the output amplifier,  $A_3$ . For applications where input common-mode range must be maximized, limit the output voltage swing by selecting a lower gain of the PGA204/205 (see performance curve "Input Common-Mode Voltage Range vs Output Voltage"). If necessary, add gain after the PGA204/205 to increase the voltage swing.



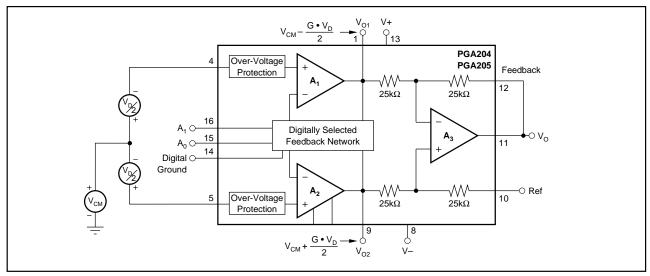


FIGURE 5. Voltage Swing of  $A_1$  and  $A_2$ .

Input-overload often produces an output voltage that appears normal. For example, consider an input voltage of +20V on one input and +40V on the other input will obviously exceed the linear common-mode range of both input amplifiers. Since both input amplifiers are saturated to the nearly the same output voltage limit, the difference voltage measured by the output amplifier will be near zero. The output of the PGA204/205 will be near 0V even though both inputs are overloaded.

#### INPUT PROTECTION

The inputs of the PGA204/205 are individually protected for voltages up to  $\pm 40 \, \mathrm{V}$ . For example, a condition of  $-40 \, \mathrm{V}$  on one input and  $+40 \, \mathrm{V}$  on the other input will not cause damage. Internal circuitry on each input provides low series impedance under normal signal conditions. To provide equivalent protection, series input resistors would contribute excessive noise. If the input is overloaded, the protection circuitry limits the input current to a safe value (approximately 1.5mA). The typical performance curve "Input Bias Current vs Common-Mode Input Voltage" shows this input current limit behavior. The inputs are protected even if no power supply voltage is present.

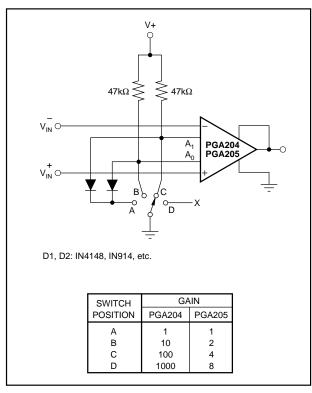


FIGURE 6. Switch-Selected PGIA.

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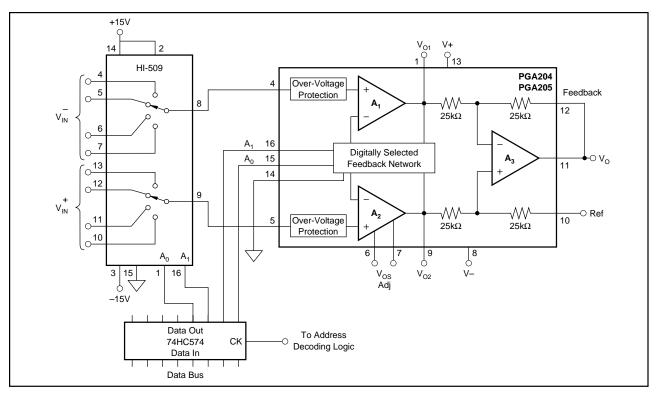


FIGURE 7. Multiplexed-Input Programmable Gain IA.

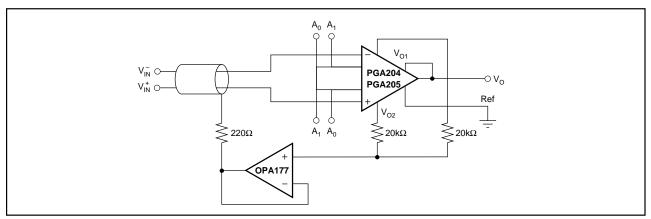


FIGURE 8. Shield Drive Circuit.

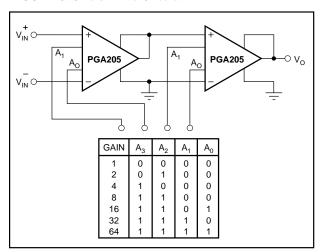


FIGURE 9. Binary Gain Steps, G=1 to G=64.

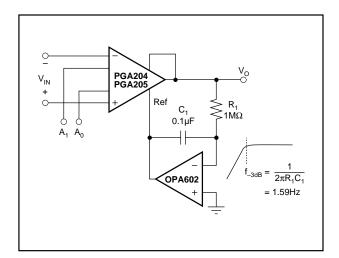


FIGURE 10. AC-Coupled PGIA.







11-Apr-2013

## **PACKAGING INFORMATION**

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Sampl
PGA204AP	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type		PGA204AP	Sampl
PGA204APG4	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type		PGA204AP	Sampl
PGA204AU	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	PGA204AU	Sampl
PGA204AU/1K	ACTIVE	SOIC	DW	16	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	PGA204AU	Sampl
PGA204AU/1KE4	ACTIVE	SOIC	DW	16	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	PGA204AU	Samp
PGA204AUE4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	PGA204AU	Samp
PGA204AUG4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	PGA204AU	Samp
PGA204BP	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type		PGA204BP	Samp
PGA204BPG4	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type		PGA204BP	Samp
PGA204BU	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR		PGA204BU	Samp
PGA204BU/1K	ACTIVE	SOIC	DW	16	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR		PGA204BU	Samp
PGA204BU/1KE4	ACTIVE	SOIC	DW	16	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR		PGA204BU	Samp
PGA204BUE4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR		PGA204BU	Samp
PGA205AP	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type		PGA205AP	Samp
PGA205APG4	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type		PGA205AP	Samp
PGA205AU	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR		PGA205AU	Samp
PGA205AU/1K	ACTIVE	SOIC	DW	16	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR		PGA205AU	Samp



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## PACKAGE OPTION ADDENDUM

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Orderable Device	Status	Package Type	•	Pins	_	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
	(1)		Drawing		Qty	(2)		(3)		(4)	
PGA205AU/1KG4	ACTIVE	SOIC	DW	16	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR		PGA205AU	Samples
PGA205AUG4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR		PGA205AU	Samples
PGA205BP	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type		PGA205BP	Samples
PGA205BPG4	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type		PGA205BP	Samples
PGA205BU	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR		PGA205BU	Samples
PGA205BUG4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR		PGA205BU	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

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<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.



## **PACKAGE OPTION ADDENDUM**

11-Apr-2013

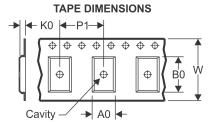
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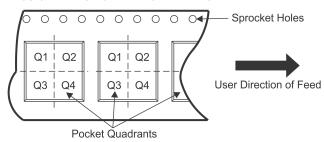
## TAPE AND REEL INFORMATION





Α0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

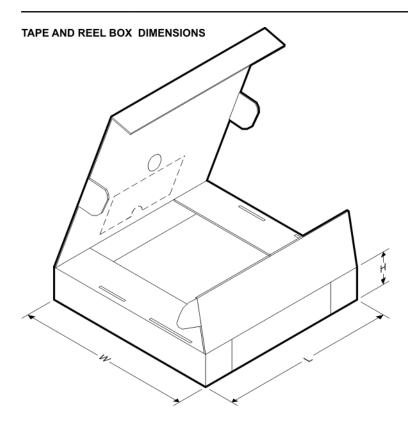


#### \*All dimensions are nominal

Device Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
PGA204AU/1K	SOIC	DW	16	1000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
PGA204BU/1K	SOIC	DW	16	1000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
PGA205AU/1K	SOIC	DW	16	1000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1

**PACKAGE MATERIALS INFORMATION** 

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#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
PGA204AU/1K	SOIC	DW	16	1000	367.0	367.0	38.0
PGA204BU/1K	SOIC	DW	16	1000	367.0	367.0	38.0
PGA205AU/1K	SOIC	DW	16	1000	367.0	367.0	38.0

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